

## ABSTRACT

A thermosetting and active energy ray curable resin composition is disclosed which contains, as active constituents, a polymer having a (meth)acryl equivalent of 100 to 300 g/eq, a hydroxyl value of 50 to 550  
5 mgKOH/g, an epoxy equivalent of 7000 g/eq or more and a weight-average molecular weight of 5000 to 100000 and a heat-curing agent. A transfer material is also disclosed which includes a protective layer formed of the heat-crosslinking reaction product of the resin composition on a base sheet. A method of producing a molded article  
10 is disclosed which includes using the transfer material to form a protective layer.